



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-04-15
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
ST8L65N044M9	P8CH*M9F85MV	A	Z4XA	2025-04-15
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	180	mg	Each	ECOPACK® 2
Identity	Authority			
Comment	0			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy		Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		0

Package designator	Package size	Number of instances	Shape	
SOT	8x8	4	gull wing	
Comment				
Comment	A0CH Power FLAT MLPD 8x8 4L			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 3rd January 2025			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.272	alloy	1511
Lead	9.077	solder	50428

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014		Response		
QUERY		Response		
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products		true		
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products		false		
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
X	O	O	O	O

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead (Pb)	1000 ppm	9.08	Soft solder	50428
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Lead dinitrate	1000 ppm	9.077	Soft solder	954971



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene, Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	P8CH*M9F85MV		180.0000		5999999.0	999999.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	10.689	mg	supplier	die	Silicon(Si)	7440-21-3		9.412	mg	880531	52289
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.397	mg	37141	2206
				supplier	metallisation	Copper(Cu)	7440-50-8		0.013	mg	1216	72
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.272	mg	25447	1511
				supplier	metallisation	Silver(Ag)	7440-22-4		0.116	mg	10852	644
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.053	mg	4958	294
				supplier	metallisation	Tungsten(W)	7440-33-7		0.106	mg	9917	589
				supplier	metallisation	Vanadium(V)	7440-62-2		0.011	mg	1029	61
				supplier	Passivation	Silicon nitride(Si3N4)	12033-89-5		0.080	mg	7484	444
				supplier	passivation	Silicon oxide(SiO2)	7631-86-9		0.229	mg	21424	1272
Leadframe	M-004 Copper and its alloys	81.996	mg	supplier	alloy	Copper (Cu)	7440-50-8		79.357	mg	967816	440872
				supplier	alloy	Iron (Fe)	7439-89-6		1.747	mg	21306	9706
				supplier	alloy	Phosphorus (P)	12185-10-3		0.019	mg	232	106
				supplier	alloy	Zinc (Zn)	7440-66-6		0.098	mg	1195	544
				supplier	alloy	Silver (Ag)	7440-22-4		0.775	mg	9452	4306
Soft solder	Solder	9.505	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high melting temper	9.077	mg	954971	50428
				supplier	solder	Silver (Ag)	7440-22-4		0.238	mg	25039	1322
				supplier	solder	Tin (Sn)	7440-31-5		0.190	mg	19989	1056
Bonding wires	M-004 Copper and its alloys	0.426	mg	supplier	wire	Copper (Cu)	7440-50-8		0.426	mg	1000000	2367
Encapsulation	M-011 Other inorganic materials	72.896	mg	supplier	mold compound	Silica Fused	60676-86-0		68.305	mg	937020	379472
				supplier	mold compound	Epoxy Resin	Proprietary		2.186	mg	29988	12144
				supplier	mold compound	Phenol resin	Proprietary		2.186	mg	29988	12144
				supplier	mold compound	Carbon Black	1333-86-4		0.219	mg	3004	1217
Connections coating	Solder	4.488	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		4.488	mg	1000000	24933